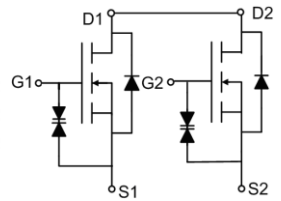


Main Product Characteristics:

V_{DS}	20V
$R_{DS(on)}$	14mΩ (typ.)
I_D	8A ^①


TSSOP-8

**Marking and pin
Assignment**

Schematic diagram
Features and Benefits:

- Advanced MOSFET process technology
- Ultra low on-resistance with low gate charge
- High Power and current handling capability
- 150°C operating temperature
- G/S ESD protect 2KV (HBM)


Description:

The SSF8810 series MOSFETs is a new technology, which combines an innovative technology and advance process. This new technology achieves low Rdson, energy saving, high reliability and uniformity, superior power density and space saving.

Absolute max Rating:

Symbol	Parameter	Max.	Units
I_D @ TC = 25°C	Continuous Drain Current	8 ^①	A
I_D @ TC = 100°C	Continuous Drain Current	6.2 ^①	
I_{DM}	Pulsed Drain Current ^②	25	
P_D @TC = 25°C	Power Dissipation ^③	2	W
	Linear Derating Factor	0.5	W/°C
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-to-Source Voltage	± 10	V
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to +150	°C

Thermal Resistance

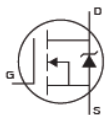
Symbol	Characteristics	Typ.	Max.	Units
$R_{\theta JA}$	Junction-to-ambient ($t \leq 10s$) ^④	—	90	°C/W

Electrical Characteristics @T_A=25°C unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
V _{(BR)DSS}	Drain-to-Source breakdown voltage	20	—	—	V	V _{GS} = 0V, I _D = 250μA
R _{DS(on)}	Static Drain-to-Source on-resistance	—	14	20	mΩ	V _{GS} =4.5V, I _D = 7A
		—	18	—		T _J = 125°C
		—	20	28	mΩ	V _{GS} =2.5V, I _D = 5.5A
		—	24	—		T _J = 125°C
		—	38	50	mΩ	V _{GS} =1.8V, I _D = 5A
		—	42	—		T _J = 125°C
V _{GS(th)}	Gate threshold voltage	0.6	—	1	V	V _{DS} = V _{GS} , I _D = 250μA
I _{DSS}	Drain-to-Source leakage current	—	—	1	μA	V _{DS} = 20V, V _{GS} = 0V
		—	—	50		T _J = 125°C
I _{GSS}	Gate-to-Source forward leakage	—	—	100	nA	V _{GS} = 4.5V
		—	—	-100		V _{GS} = -4.5V
		—	—	10	uA	V _{GS} = 10V
		—	—	-10		V _{GS} = -10V
Q _g	Total gate charge	—	10	—	nC	I _D = 7A, V _{DS} =10V, V _{GS} = 4.5V
Q _{gs}	Gate-to-Source charge	—	2.3	—		
Q _{gd}	Gate-to-Drain("Miller") charge	—	3	—		
t _{d(on)}	Turn-on delay time	—	7.3	—	ns	V _{GS} =4.5V, V _{DS} =10V, R _{GEN} =3Ω, I _D =6.5
t _r	Rise time	—	60	—		
t _{d(off)}	Turn-Off delay time	—	18	—		
t _f	Fall time	—	5.9	—		
C _{iss}	Input capacitance	—	632	—	pF	V _{GS} = 0V
C _{oss}	Output capacitance	—	142	—		V _{DS} = 10V
C _{rss}	Reverse transfer capacitance	—	134	—		f = 1MHz

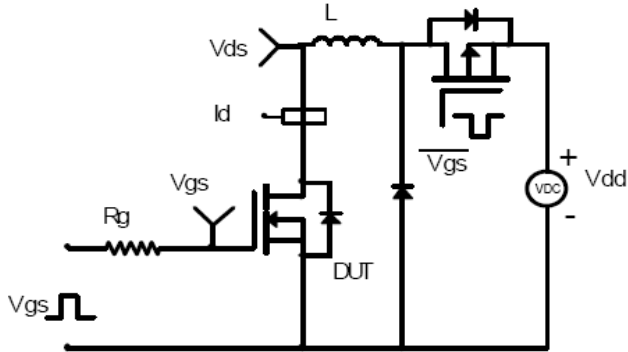
Source-Drain Ratings and Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
I _S	Continuous Source Current (Body Diode)	—	—	8 ①	A	MOSFET symbol showing the integral reverse p-n junction diode.
I _{SM}	Pulsed Source Current (Body Diode)	—	—	25	A	
V _{SD}	Diode Forward Voltage	—	—	1.2	V	I _S =2.8A, V _{GS} =0V
t _{rr}	Reverse Recovery Time	—	35	—	nS	T _J = 25°C, I _F =7A, di/dt = 100A/μs
Q _{rr}	Reverse Recovery Charge	—	7.2	—	nC	

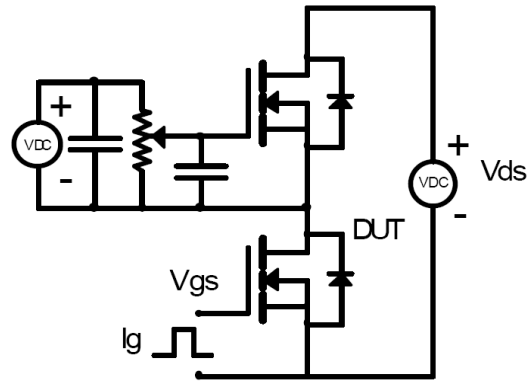


Test circuits and Waveforms

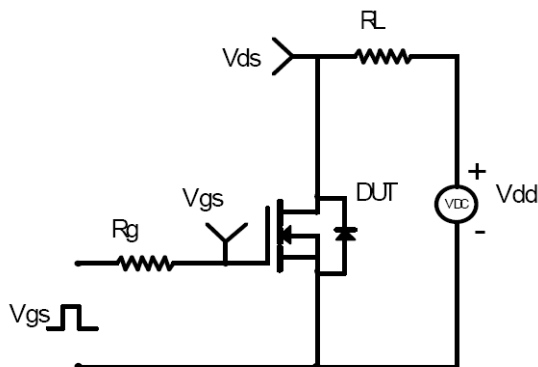
EAS Test Circuit:



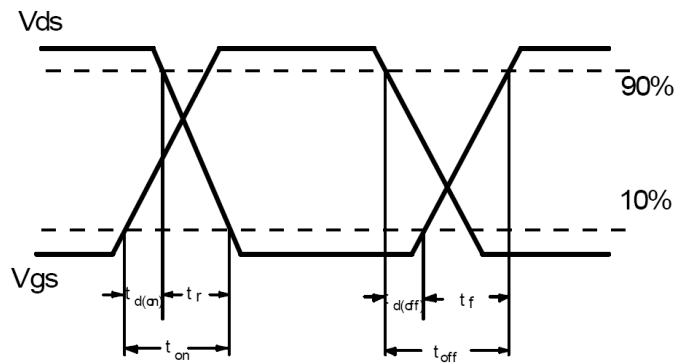
Gate charge test circuit:



Switching Time Test Circuit:



Switching Waveforms:



Notes:

- ① Calculated continuous current based on maximum allowable junction temperature.
- ② Repetitive rating; pulse width limited by max. junction temperature.
- ③ The power dissipation PD is based on max. junction temperature, using junction-to-case thermal resistance.
- ④ The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$

Typical electrical and thermal characteristics

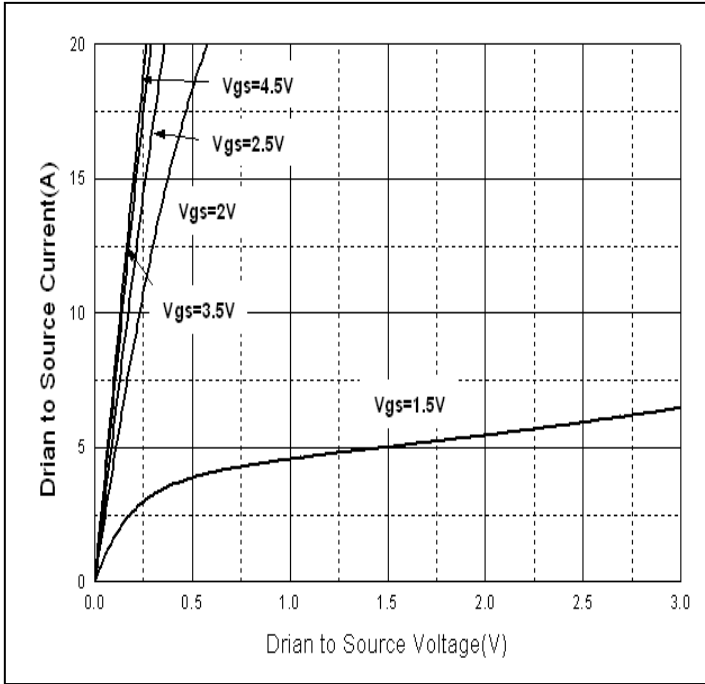


Figure 1: Typical Output Characteristics

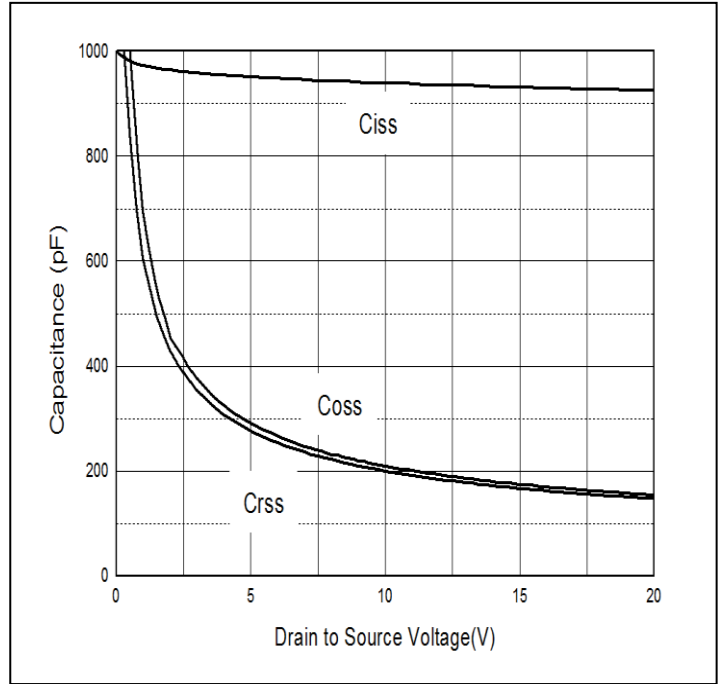


Figure2. Typical Capacitance Vs. Drain-to-Source Voltage

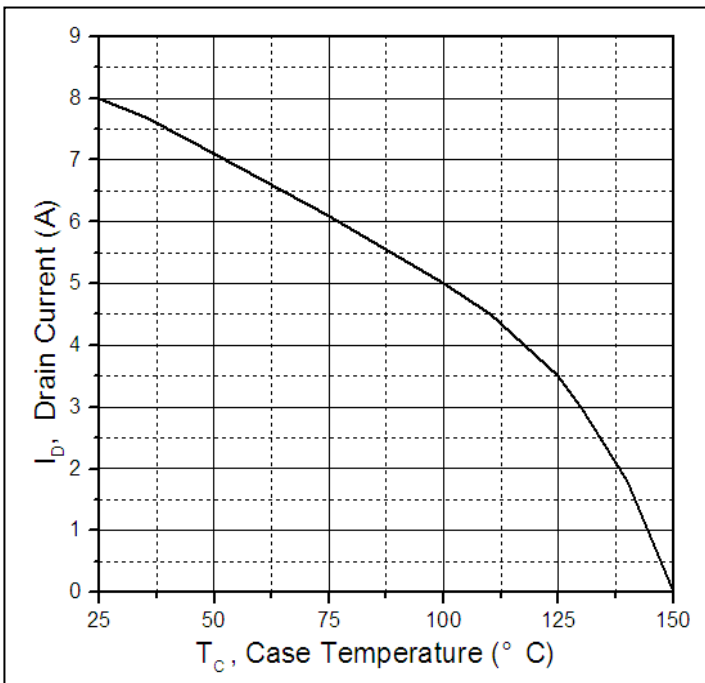


Figure 3. Maximum Drain Current Vs. Case Temperature

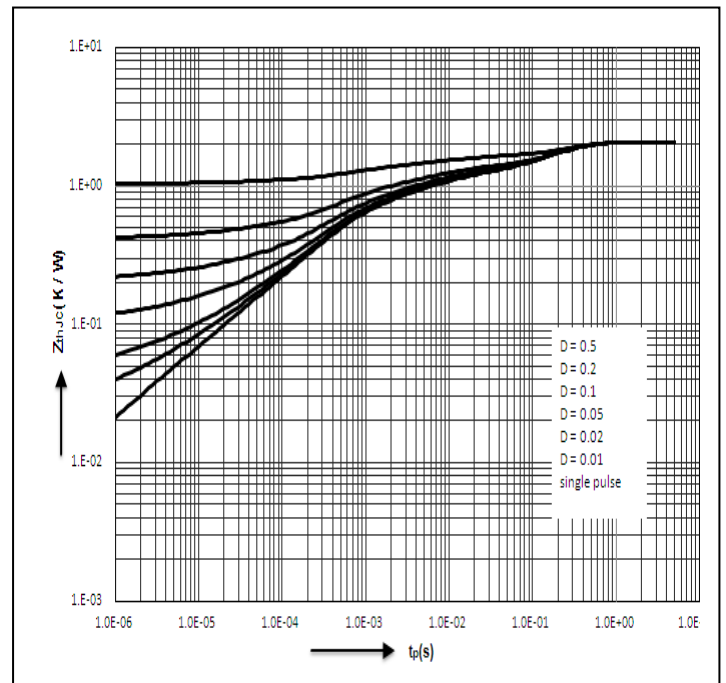
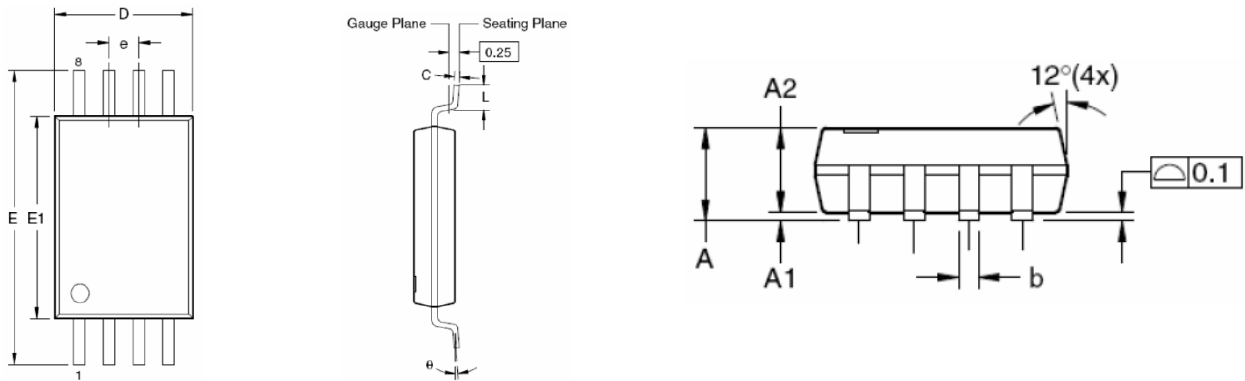
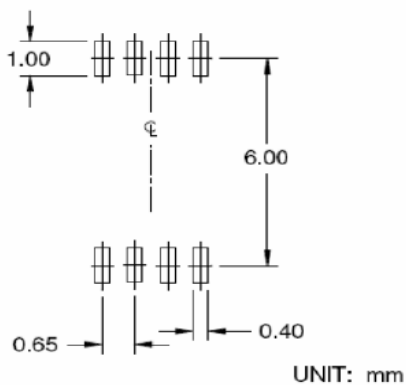


Figure4. Maximum Effective Transient Thermal Impedance, Junction-to-Case

Mechanical Data:
TSSOP-8 Dimensions in Millimeters (UNIT:mm)

RECOMMENDED LAND PATTERN

Dimensions in millimeters

Symbols	Min.	Nom.	Max.
A	—	—	1.20
A1	0.05	—	0.15
A2	0.80	1.00	1.05
b	0.19	—	0.30
C	0.09	—	0.20
D	2.90	3.00	3.10
E	6.40 BSC		
E1	4.30	4.40	4.50
e	0.65 BSC		
L	0.45	0.60	0.75
θ	0°	—	8°

Dimensions in inches

Symbols	Min.	Nom.	Max.
A	—	—	0.047
A1	0.002	—	0.006
A2	0.031	0.039	0.041
b	0.007	—	0.012
C	0.004	—	0.008
D	0.114	0.118	0.122
E	0.252 BSC		
E1	0.169	0.173	0.177
e	0.026 BSC		
L	0.018	0.024	0.030
θ	0°	—	8°

NOTES:

1. All dimensions are in millimeters.
2. Dimensions are inclusive of plating
3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 6 mils.
4. Dimension L is measured in gauge plane.
5. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.

Ordering and Marking Information**Device Marking: SSF8810**

Package (Available)
TSSOP-8
Operating Temperature Range
C : -55 to 150 °C

Devices per Unit

Package Type	Units/ Tube	Tubes/Inner Box	Units/Inner Box	Inner Boxes/ Carton Box	Units/ Carton Box
TSSOP-8	3000	2	6000	8	48000

Reliability Test Program

Test Item	Conditions	Duration	Sample Size
High Temperature Reverse Bias(HTRB)	$T_j=125^{\circ}\text{C}$ to 150°C @ 80% of Max $V_{DSS}/V_{CES}/V_R$	168 hours 500 hours 1000 hours	3 lots x 77 devices
High Temperature Gate Bias(HTGB)	$T_j=150^{\circ}\text{C}$ @ 100% of Max V_{GSS}	168 hours 500 hours 1000 hours	3 lots x 77 devices

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